

Title (en)  
Integral audio module

Title (de)  
Integriertes Audio-Modul

Title (fr)  
Module audio intégrée

Publication  
**EP 1722592 A1 20061115 (EN)**

Application  
**EP 05010028 A 20050509**

Priority  
EP 05010028 A 20050509

Abstract (en)  
An integral audio module includes a housing having a chamber therein and a hole. A diaphragm received in the chamber of the housing to divide the chamber into a front chamber and a rear chamber. The diaphragm has a coil in the rear chamber of the housing. A magnetic assembly is received in the rear chamber to vibrate the diaphragm. The magnetic assembly has a damping chamber with a damping material therein, a first aperture communicating the damping chamber with the rear chamber and a second aperture communicating the damping chamber with outside of the housing.

IPC 8 full level  
**H04R 1/10** (2006.01); **H04R 1/22** (2006.01)

CPC (source: EP)  
**H04R 1/1016** (2013.01); **H04R 1/225** (2013.01)

Citation (search report)

- [X] US 4742887 A 19880510 - YAMAGISHI MAKOTO [JP]
- [X] EP 0909110 A2 19990414 - NOKIA MOBILE PHONES LTD [FI]
- [A] EP 0448110 A2 19910925 - SHARP KK [JP]
- [X] PATENT ABSTRACTS OF JAPAN vol. 009, no. 305 (E - 363) 3 December 1985 (1985-12-03)

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Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)  
AL BA HR LV MK YU

DOCDB simple family (publication)  
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